

RD100HHF1C

RoHS Compliance, Silicon MOSFET Power Transistor 30MHz,100W

DESCRIPTION

RD100HHF1C is a MOS FET type transistor specifically designed for HF High power amplifiers applications.

FEATURES

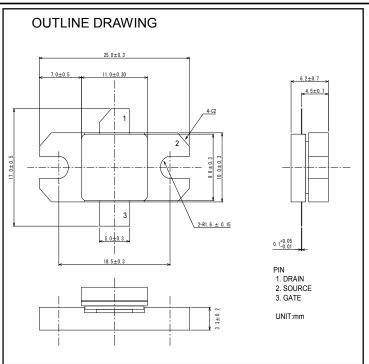
High power and High Gain:

 P_{out} >100W, G_p >11.5dB @ V_{DD} =12.5V,f=30MHz

High Efficiency: 60%typ.on HF Band

APPLICATION

For output stage of high power amplifiers in HF Band mobile radio sets.



RoHS COMPLIANT

RD100HHF1C-501 is a RoHS compliant products.

ABSOLUTE MAXIMUM RATINGS

(Tc=25°C UNLESS OTHERWISE NOTED)

SYMBOL	PARAMETER	CONDITIONS	RATINGS	UNIT
V_{DSS}	Drain to source voltage	V _{GS} =0V	50	V
V_{GSS}	Gate to source voltage	V _{DS} =0V	+/-20	V
P _{ch}	Channel dissipation	T _c =25°C	176.5	W
P _{in}	Input power	$Z_G=Z_L=50\Omega$	12.5	W
I _D	Drain current	-	25	Α
T _{ch}	Channel temperature	-	175	°C
T _{stg}	Storage temperature	-	-40 to +175	°C
R _{th j-c}	Thermal resistance	junction to case	0.85	°C/W

Note 1: Above parameters are guaranteed independently.

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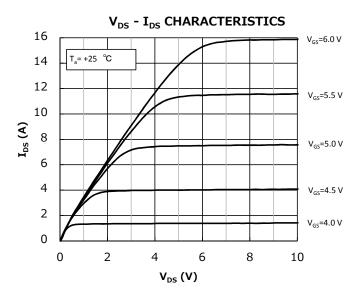
ELECTRICAL CHARACTERISTICS (T_c=25°C UNLESS OTHERWISE NOTED)

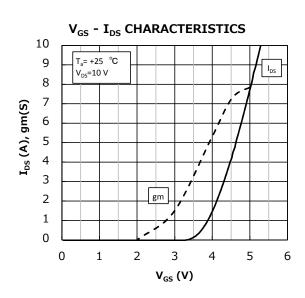
SYMBOL	PARAMETER	CONDITIONS	LIMITS			UNIT
	PARAIVIETER	CONDITIONS	MIN	TYP	MAX.	
I _{DSS}	Zerogate voltage drain current	V _{DS} =17V, V _{GS} =0V	ı	-	10	uA
I _{GSS}	Gate to source leak current	V _{GS} =10V, V _{DS} =0V	ı	-	1	uA
V_{TH}	Gate threshold voltage	V _{DS} =12V, I _{DS} =1mA	1.5	-	4.5	V
P _{out}	Output power	f=30MHz ,V _{DD} =12.5V	100	110	-	W
η_{D}	Drain efficiency	P _{in} =7W, I _{DQ} =1.0A	55	60	-	%
	Load VSWR tolerance	V _{DD} =15.2V,P _{out} =100W(P _{in} Control)	No destroy		-	
		f=30MHz, I_{DQ} =1.0A, Z_{G} =50 Ω				
		Load VSWR=20:1(All Phase)				

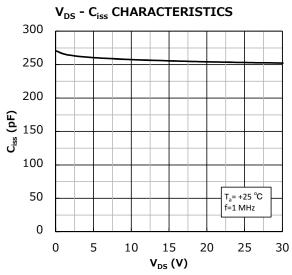
Note: Above parameters, ratings, limits and conditions are subject to change.

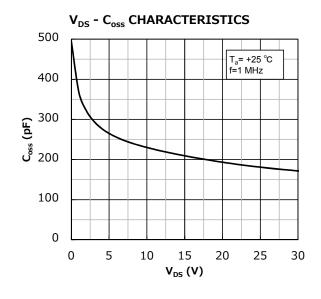
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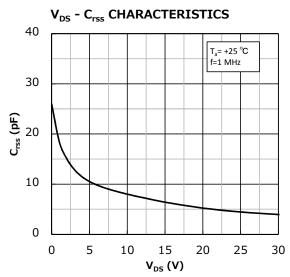
TYPICAL CHARACTERISTICS





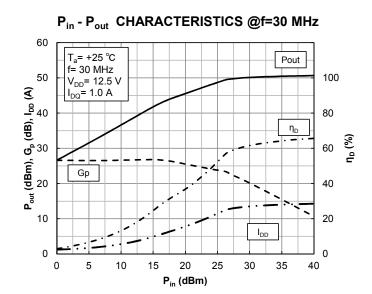


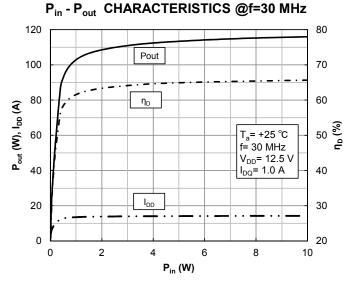


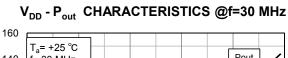


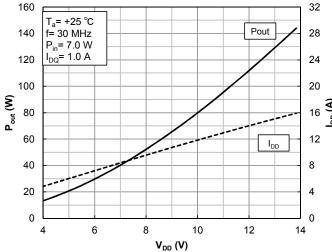
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TYPICAL CHARACTERISTICS



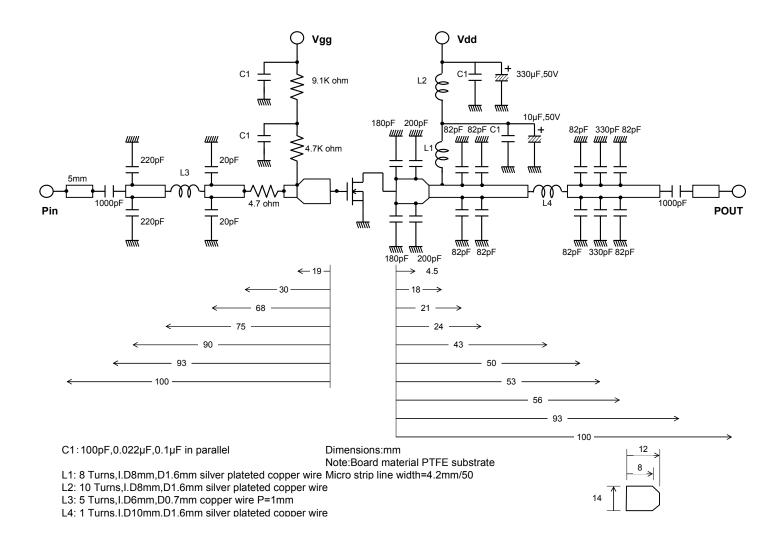






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TEST CIRCUIT(f=30MHz)



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RD100HHF1C S-PARAMETER DATA (@V_{DS}=12.5V, I_{DQ}=800mA)

Freq.	S11		S21		S12		S22	
(MHz)	(mag)	(ang)	(mag)	(ang)	(mag)	(ang)	(mag)	(ang)
10	0.984	-156.8	55.469	101.2	0.010	11.7	0.724	-157.2
20	0.848	-167.4	26.743	87.2	0.009	-0.9	0.771	-167.5
30	0.830	-170.2	17.376	79.6	0.009	-8.1	0.783	-169.9
40	0.829	-171.2	12.668	73.6	0.008	-13.1	0.798	-170.6
50	0.835	-171.7	9.819	68.3	0.008	-18.2	0.810	-170.9
60	0.844	-172.0	7.901	63.6	0.008	-21.8	0.824	-171.2
70	0.854	-172.3	6.520	59.3	0.007	-25.7	0.837	-171.1
80	0.863	-172.6	5.477	55.4	0.007	-29.0	0.849	-171.3
90	0.873	-172.9	4.669	51.8	0.006	-31.8	0.863	-171.6
100	0.881	-173.2	4.018	48.6	0.006	-34.1	0.873	-171.9
150	0.915	-174.9	2.166	36.0	0.004	-39.5	0.918	-173.6
200	0.934	-176.7	1.335	27.3	0.003	-40.5	0.943	-175.3
250	0.942	-178.2	0.899	21.4	0.002	-22.8	0.960	-176.9
300	0.944	-179.3	0.642	16.7	0.001	23.4	0.971	-178.2
350	0.945	180.0	0.483	13.3	0.001	58.4	0.975	-179.6
400	0.950	179.5	0.379	10.5	0.002	72.1	0.978	179.3
450	0.958	178.7	0.304	7.8	0.003	80.9	0.980	178.3
500	0.963	177.8	0.248	6.1	0.004	82.7	0.977	177.4
550	0.966	177.0	0.207	4.6	0.004	83.4	0.972	176.8
600	0.969	176.2	0.177	3.2	0.005	84.2	0.974	176.4
650	0.970	175.4	0.152	1.2	0.006	83.7	0.976	175.9
700	0.971	174.7	0.131	-0.4	0.007	84.4	0.977	175.4
750	0.973	174.0	0.118	0.2	0.007	83.7	0.981	174.7
800	0.973	173.2	0.105	-1.0	0.008	83.5	0.982	174.0
850	0.974	172.5	0.090	-3.7	0.009	84.5	0.982	173.2
900	0.975	171.8	0.081	-3.1	0.010	82.4	0.983	172.6
950	0.975	171.0	0.071	-3.8	0.011	82.0	0.982	172.1
1000	0.977	170.3	0.064	-2.2	0.011	81.6	0.978	171.5

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ATTENTION:

- 1.High Temperature; This product might have a heat generation while operation, Please take notice that have a possibility to receive a burn to touch the operating product directly or touch the product until cold after switch off. At the near the product, do not place the combustible material that have possibilities to arise the fire.
- 2.Generation of High Frequency Power; This product generate a high frequency power. Please take notice that do not leakage the unnecessary electric wave and use this products without cause damage for human and property per normal operation.
- 3.Before use; Before use the product, Please design the equipment in consideration of the risk for human and electric wave obstacle for equipment.

PRECAUTIONS FOR THE USE OF MITSUBISHI SILICON RF POWER DEVICES:

- 1. The specifications of mention are not guarantee values in this data sheet. Please confirm additional details regarding operation of these products from the formal specification sheet. For copies of the formal specification sheets, please contact one of our sales offices.
- 2.RA series products (RF power amplifier modules) and RD series products (RF power transistors) are designed for consumer mobile communication terminals and were not specifically designed for use in other applications. In particular, while these products are highly reliable for their designed purpose, they are not manufactured under a quality assurance testing protocol that is sufficient to guarantee the level of reliability typically deemed necessary for critical communications elements and In the application, which is base station applications and fixed station applications that operate with long term continuous transmission and a higher on-off frequency during transmitting, please consider the derating, the redundancy system, appropriate setting of the maintain period and others as needed. For the reliability report which is described about predicted operating life time of Mitsubishi Silicon RF Products, please contact Mitsubishi Electric Corporation or an authorized Mitsubishi Semiconductor product distributor.
- 3. RD series products use MOSFET semiconductor technology. They are sensitive to ESD voltage therefore appropriate ESD precautions are required.
- 4. In the case of use in below than recommended frequency, there is possibility to occur that the device is deteriorated or destroyed due to the RF-swing exceed the breakdown voltage.
- 5. In order to maximize reliability of the equipment, it is better to keep the devices temperature low. It is recommended to utilize a sufficient sized heat-sink in conjunction with other cooling methods as needed (fan, etc.) to keep the channel temperature for RD series products lower than 120deg/C(in case of Tchmax=150deg/C) ,140deg/C(in case of Tchmax=175deg/C) under standard conditions.
- 6. Do not use the device at the exceeded the maximum rating condition. In case of plastic molded devices, the exceeded maximum rating condition may cause blowout, smoldering or catch fire of the molding resin due to extreme short current flow between the drain and the source of the device. These results causes in fire or injury.
- 7. For specific precautions regarding assembly of these products into the equipment, please refer to the supplementary items in the specification sheet.
- 8. Warranty for the product is void if the products protective cap (lid) is removed or if the product is modified in any way from it's original form.
- 9. For additional "Safety first" in your circuit design and notes regarding the materials, please refer the last page of this data sheet.

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- 10. Please avoid use in the place where water or organic solvents can adhere directly to the product and the environments with the possibility of caustic gas, dust, salinity, etc. Reliability could be markedly decreased and also there is a possibility failures could result causing a serious accident. Likewise, there is a possibility of causing a serious accident if used in an explosive gas environment. Please allow for adequate safety margin in your designs.
- 11. Please refer to the additional precautions in the formal specification sheet.

Keep safety first in your circuit designs!

Mitsubishi Electric Corporation puts the maximum effort into making semiconductor products better and more reliable, but there is always the possibility that trouble may occur with them. Trouble with semiconductors may lead to personal injury, fire or property damage. Remember to give due consideration to safety when making your circuit designs, with appropriate measures such as (i) placement of substitutive, auxiliary circuits, (ii) use of non-flammable material or (iii) prevention against any malfunction or mishap.

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